



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

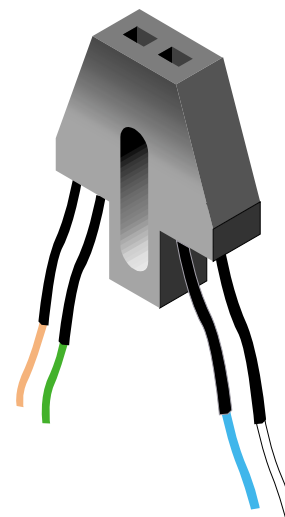
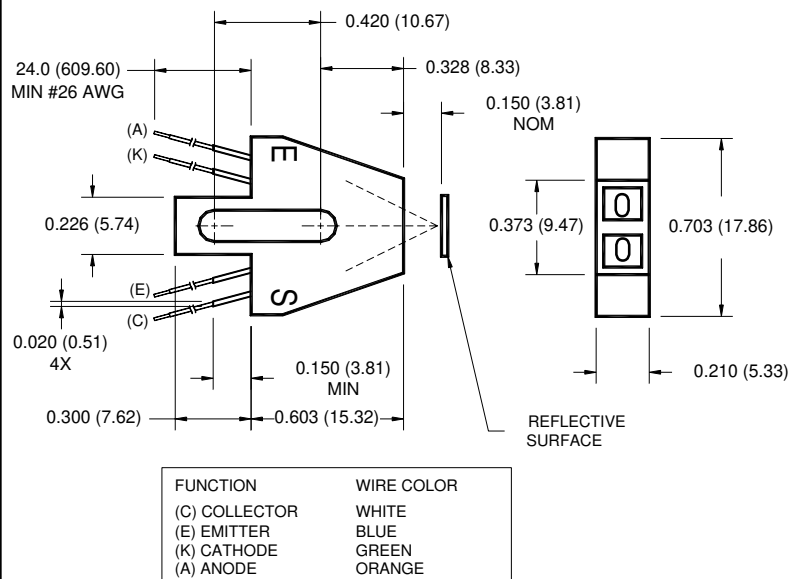
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

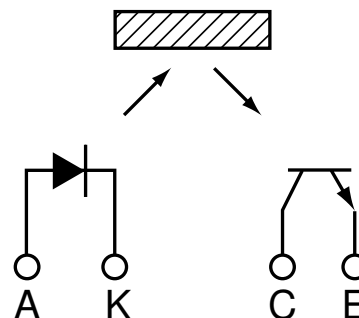
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PACKAGE DIMENSIONS



SCHEMATIC



NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.

DESCRIPTION

The QRC1133 consists of an infrared emitting diode and an NPN silicon phototransistor mounted side by side on a converging optical axis in a black plastic housing. The phototransistor responds to radiation from the emitting diode only when a reflective object passes within its field of view. The area of the optimum response approximates a circle .200" in diameter.

FEATURES

- Phototransistor output
- High Sensitivity
- Low cost plastic housing
- #26 AWG, 24 inch PVC wire termination

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Units
Operating Temperature	T_{OPR}	-40 to +85	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40 to +85	$^\circ\text{C}$
Soldering Temperature (Iron) ^(2,3,4)	T_{SOL-I}	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) ^(2,3)	T_{SOL-F}	260 for 10 sec	$^\circ\text{C}$
EMITTER			
Continuous Forward Current	I_F	50	mA
Reverse Voltage	V_R	5	V
Power Dissipation ⁽¹⁾	P_D	100	mW
SENSOR			
Collector-Emitter Voltage	V_{CEO}	30	V
Emitter-Collector Voltage	V_{ECO}	5	V
Collector Current	I_C	20	mA
Power Dissipation ⁽¹⁾	P_D	100	mW

NOTES

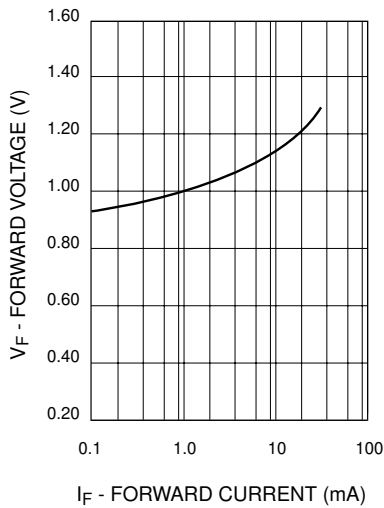
- Derate power dissipation linearly 1.67 mW/ $^\circ\text{C}$ above 25°C .
- RMA flux is recommended.
- Methanol or isopropyl alcohols are recommended as cleaning agents.
- Soldering iron 1/16" (1.6mm) minimum from housing.
- D is the distance from the assembly face to the reflective surface.
- Cross talk is the photo current measured with current to the input diode and no reflecting surface.
- Measured using an Eastman Kodak neutral test card with 90% diffused reflecting surface.

ELECTRICAL / OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

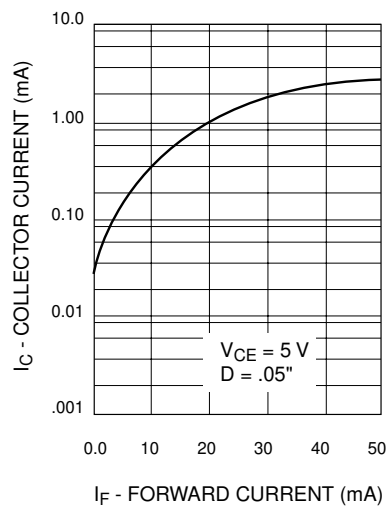
PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
EMITTER						
Forward Voltage	$I_F = 40 \text{ mA}$	V_F	—	—	1.7	V
Reverse Current	$V_R = 2.0 \text{ V}$	I_R	—	—	100	μA
Peak Emission Wavelength	$I_F = 20 \text{ mA}$	λ_{PE}	—	940	—	nm
SENSOR						
Collector-Emitter Breakdown Voltage	$I_C = 1 \text{ mA}$	BV_{CEO}	30	—	—	V
Emitter-Collector Breakdown Voltage	$I_E = 0.1 \text{ mA}$	BV_{ECO}	5	—	—	V
Collector-Emitter Dark Current	$V_{CE} = 10 \text{ V}, I_F = 0 \text{ mA}$	I_{CEO}	—	—	100	nA
COUPLED						
On-state Collector Current	$I_F = 40 \text{ mA}, V_{CE} = 5 \text{ V}, D = .150''^{(5,6)}$	$I_{C(ON)}$	0.20	—	—	mA
Collector-Emitter Saturation Voltage	$I_F = 40 \text{ mA}, I_C = 0.1 \text{ mA}$ $D = 1.50''^{(5,7)}$	$V_{CE(SAT)}$	—	—	0.4	V
Rise Time	$V_{CE} = 5 \text{ V}, R_L = 100 \Omega$	t_r	—	8	—	μs
Fall Time	$I_{C(ON)} = 5 \text{ mA}$	t_f	—	8	—	μs
Crosstalk	$I_F = 40 \text{ mA}, V_{CE} = 5 \text{ V}^{(7)}$	I_{CX}	—	—	1.00	μA

TYPICAL PERFORMANCE CURVES

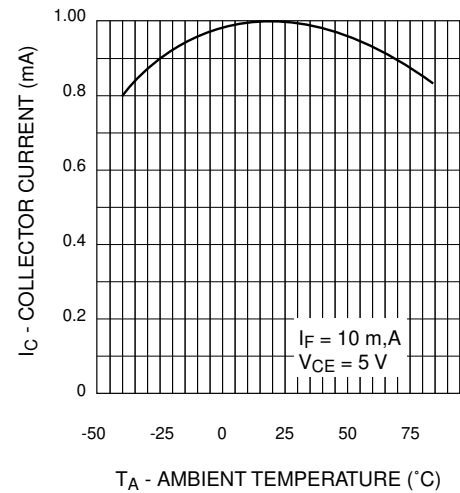
**Fig. 1 Forward Voltage
vs. Forward Current**



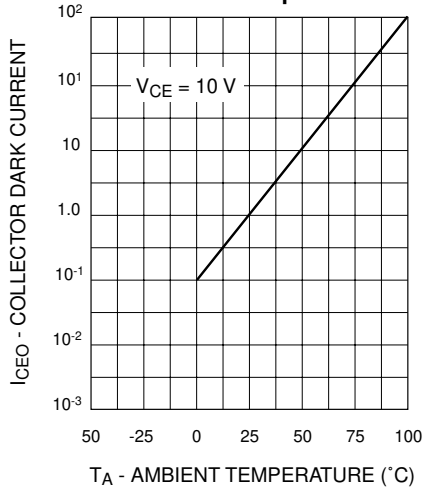
**Fig. 2 Normalized Collector Current
vs. Forward Current**



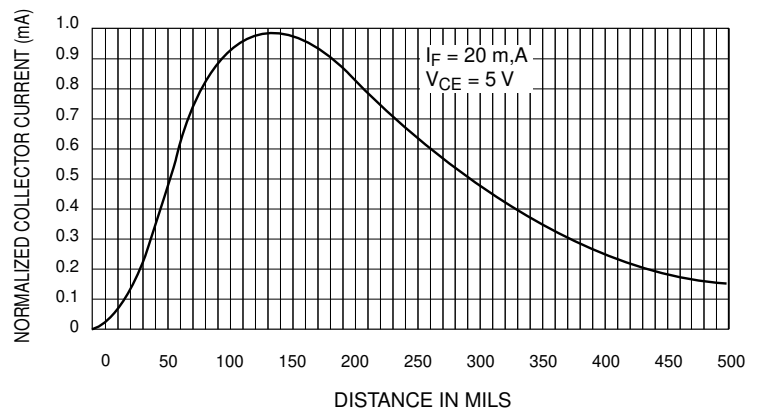
**Fig. 3 Normalized Collector Current
vs. Temperature**



**Fig. 4 Normalized Collector Dark
Current vs. Temperature**



**Fig. 5 Normalized Collector Current
vs. Distance**



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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.